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**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

IN RE APPLICATION OF: Ekkehard MUEH, et al.

SERIAL NO.: NEW U.S. PCT APPLICATION

FILED: HERewith

INTERNATIONAL APPLICATION NO.: PCT/EP04/53669

INTERNATIONAL FILING DATE: December 22, 2004

FOR: SILICON COMPOUNDS FOR PRODUCING SIO<sub>2</sub>-CONTAINING INSULATING LAYERS ON CHIPS

**REQUEST FOR PRIORITY UNDER 35 U.S.C. 119**  
**AND THE INTERNATIONAL CONVENTION**

Commissioner for Patents  
Alexandria, Virginia 22313

Sir:

In the matter of the above-identified application for patent, notice is hereby given that the applicant claims as priority:

<b><u>COUNTRY</u></b>	<b><u>APPLICATION NO</u></b>	<b><u>DAY/MONTH/YEAR</u></b>
Germany	10 2004 008 442.4	19 February 2004

Certified copies of the corresponding Convention application(s) were submitted to the International Bureau in PCT Application No. PCT/EP04/53669. Receipt of the certified copy(s) by the International Bureau in a timely manner under PCT Rule 17.1(a) has been acknowledged as evidenced by the attached PCT/IB/304.

Respectfully submitted,  
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